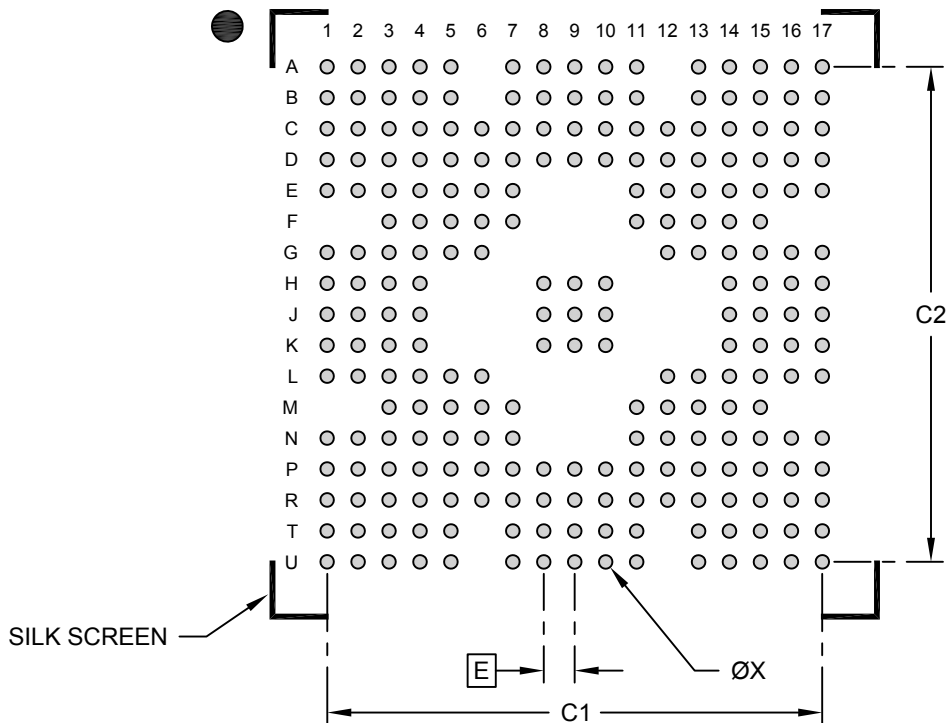


233-Ball Thin Fine Pitch Ball Grid Array (4FB) - 14x14 mm Body [TFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Contact Pitch	E		0.80 BSC		
Contact Pad Spacing	C1			12.80	
Contact Pad Spacing	C2			12.80	
Contact Pad Width (Xnn)	X1				0.35

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.